

Attorney Docket No. MIO 0020 VA (97-0198.02)
Serial No. - 09/510,828

VERSION WITH MARKINGS TO SHOW CHANGES MADE

29. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor; and

an attachment device ~~arranged to press said semiconductor against said interconnect structure to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including an elastic member comprised of a first elastomeric material, and a conductive member, said attachment device arranged to press said semiconductor between said spring element and said interconnect structure to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device.~~

54. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor; and

an attachment device ~~pressing~~arranged to press said interconnect structure against said semiconductor to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including a first conductive member, a first elastic member and a second elastic member, said first elastic member comprising a first elastomeric material having first force transfer characteristics and said second elastic member comprising a second elastomeric material having second force transfer characteristics, said second elastic member being positioned within said first elastic

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member such that said spring element has overall force transfer characteristics different from said first and second force transfer characteristics.

68. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor; and

an attachment device pressing arranged to press said interconnect structure against said semiconductor to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including a conductive member and an elastic member having a variable spring constant.

73. (Amended) The An apparatus of claim 29, for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor; and

an attachment device arranged to press said semiconductor against said interconnect structure to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including an elastic member comprised of a first elastomeric material, and a conductive member, wherein said conductive member comprises carbon.